

HEXFRED ULTRAFAST, SOFT RECOVERY DIODE

$$V_R = 200V$$

$$I_{F(AV)} = 60A$$

$$t_{rr} = 50ns$$

Features

- Reduced RFI and EMI
- Extensive Characterization of Recovery Parameters
- Hermetically Sealed
- Surface Mount
- ESD Rating: Class 3B per MIL-STD-750, Method 1020

Description

These ultrafast, soft recovery diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

Absolute Maximum Ratings

Characteristics	Parameter	Max.	Units
V_R	Cathode to Anode Voltage	200	V
$I_F @ T_C = 100^\circ C$	Continuous Forward Current ①	60	A
$I_{FSM} @ T_C = 25^\circ C$	Single Pulse Forward Current ②	500	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	125	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ C$

Notes:

① D.C. = 50% rectangle wave

② 1/2 sine wave, 60Hz, Pulse Width = 8.33ms

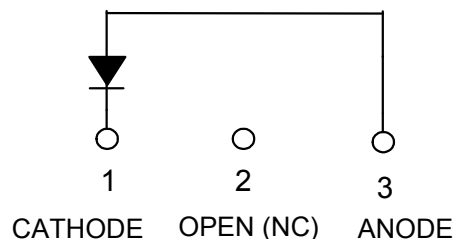
CASE STYLE



SupIR-SMD

PAD ASSIGNMENTS

(ISOLATED BASE)



Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V_{BR}	Cathode Anode Breakdown Voltage	200	—	—	V	$I_R = 100\mu\text{A}$
V_{FM}	Max. Forward Voltage See Fig. 1	—	—	1.15	V	$I_F = 30\text{A}, T_J = -55^\circ\text{C}$
		—	—	0.97		$I_F = 30\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.08		$I_F = 60\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.30		$I_F = 120\text{A}, T_J = 25^\circ\text{C}$
		—	—	0.8		$I_F = 30\text{A}, T_J = 125^\circ\text{C}$
I_{RM}	Max. Reverse Leakage Current See Fig. 2	—	—	50	μA	$V_R = V_R \text{ Rated}$
		—	—	1.0	mA	$V_R = V_R \text{ Rated}, T_J = 125^\circ\text{C}$
C_T	Junction Capacitance, See Fig. 3	—	—	200	pF	$V_R = 200\text{V}$
L_S	Series Inductance	—	5.9	—	nH	Measured from center of cathode pad the center of anode pad

Dynamic Recovery Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions	
t_{rr1}	Reverse Recovery Time	—	45	50	ns	$T_J = 25^\circ\text{C}$	$I_F = 60\text{A}$
t_{rr2}	See Fig. 5	—	71	—		$T_J = 125^\circ\text{C}$	
I_{RRM1}	Peak Recovery Current	—	5.3	—	A	$T_J = 25^\circ\text{C}$	$V_R = 160\text{V}$
I_{RRM2}	See Fig. 6	—	10.3	—		$T_J = 125^\circ\text{C}$	
Q_{rr1}	Reverse Recovery Charge	—	120	—	nC	$T_J = 25^\circ\text{C}$	$di_f/dt = 200\text{A}/\mu\text{s}$
Q_{rr2}	See Fig. 7	—	366	—		$T_J = 125^\circ\text{C}$	
$di_{(rec)M}/dt1$	Peak Rate of Fall of Recovery Current	—	590	—	A/ μs	$T_J = 25^\circ\text{C}$	
$di_{(rec)M}/dt1$	During t_b - See Fig. 8	—	1290	—		$T_J = 125^\circ\text{C}$	

Thermal - Mechanical Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	1.0	$^\circ\text{C}/\text{W}$
Wt	Weight	3.0	—	g

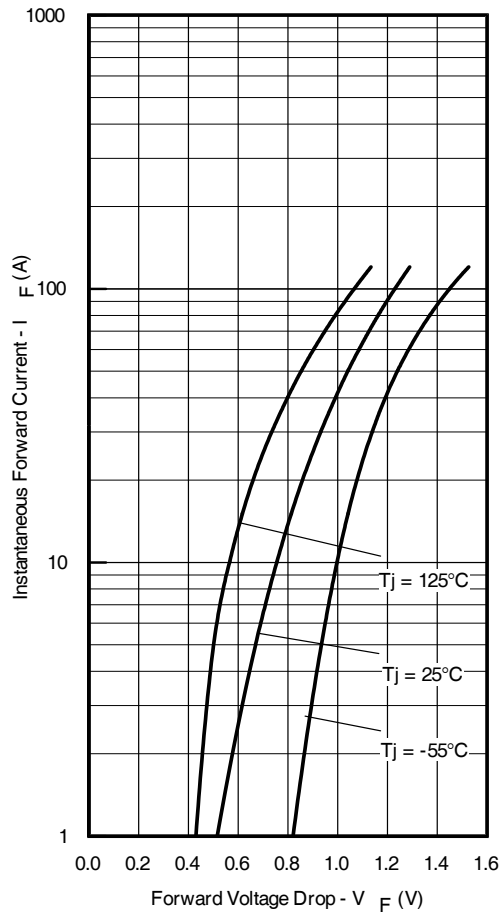


Fig. 1 Maximum Forward Voltage Drop Vs. Instantaneous Forward Current

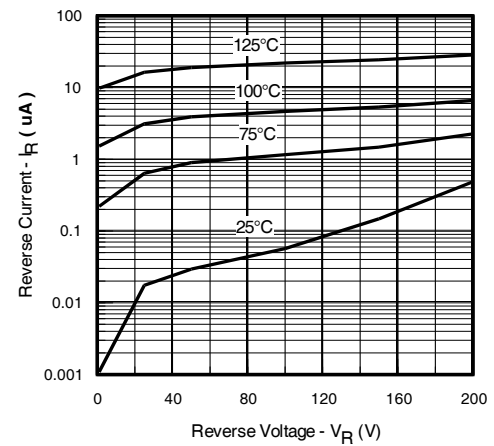


Fig. 2 Typical Values of Reverse Current Vs. Reverse Voltage

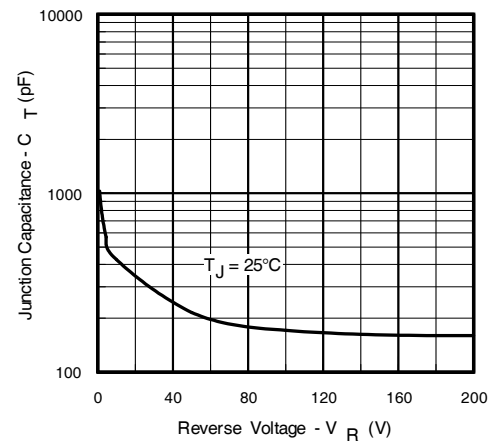


Fig. 3 Typical Junction Capacitance Vs. Reverse Voltage

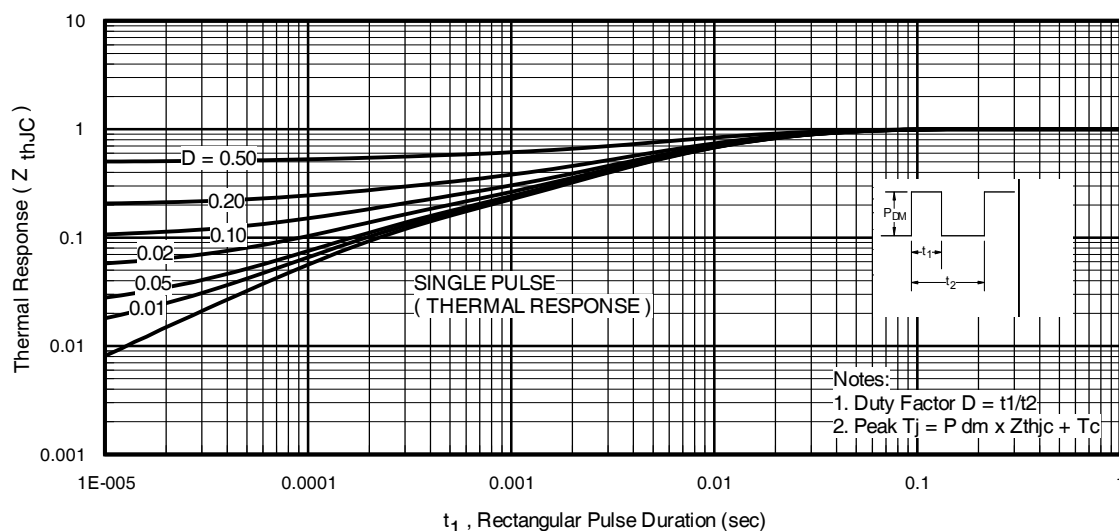


Fig. 4 Maximum Thermal Impedance Z_{thJC} Characteristics

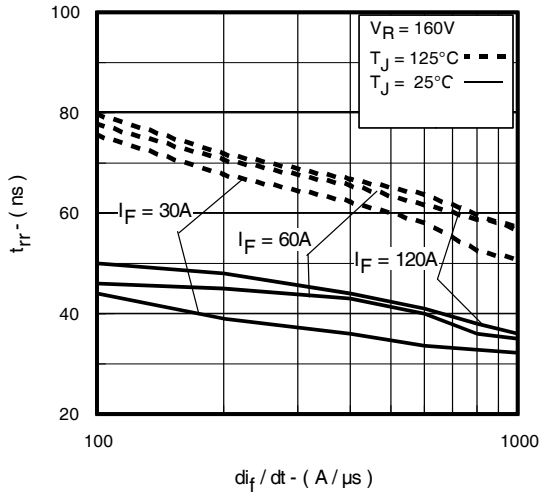


Fig. 5 Typical Reverse Recovery Vs di_f/dt

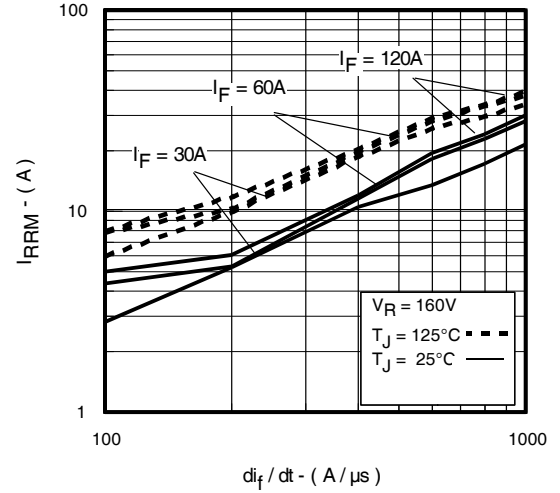


Fig. 6 Typical Recovery Current Vs di_f/dt

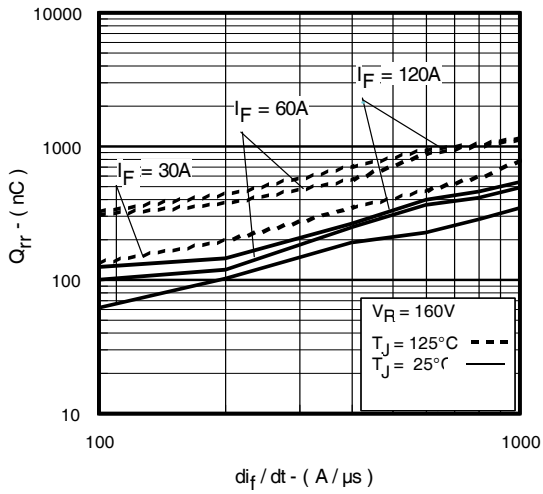


Fig. 7 Typical Stored Charge Vs di_f/dt

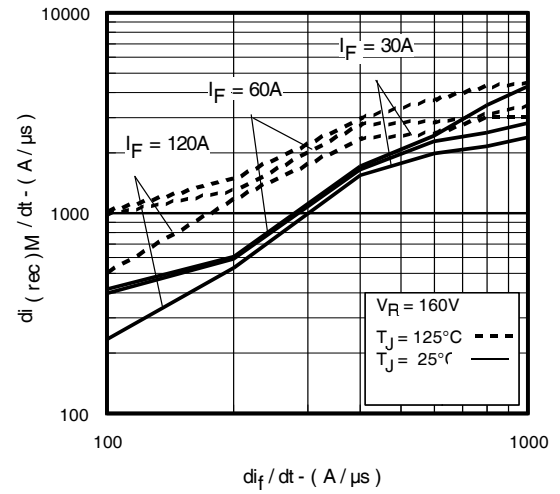


Fig. 8 Typical $di_{(rec)M}/dt$ Vs di_f/dt

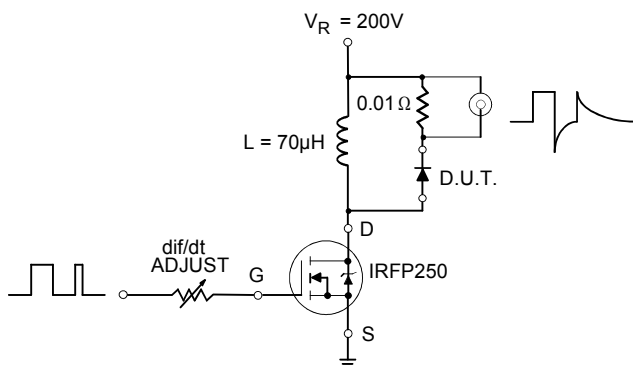
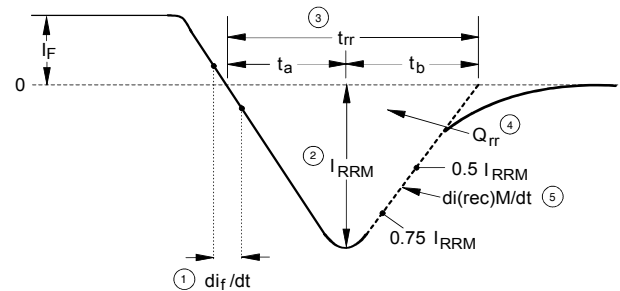


Fig. 9 Typical Reverse Recovery Parameter Test Circuit



- ① di_f/dt - Rate of change of current through zero crossing.
- ② I_{RRM} - Peak reverse recovery current.
- ③ t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75I_{RRM}$ and $0.5I_{RRM}$ extrapolated to zero current.
- ④ Q_{rr} - Area under curve defined by t_{rr} and I_{RRM} - $Q_{rr} = (t_{rr} \times I_{RRM}) / 2$
- ⑤ $di_{(rec)M}/dt$ - Peak rate of change of current during t_b position of t_{rr} .

Fig. 10 Reverse Recovery Waveform and Definitions

Technical drawing of a 1206 package showing top, side, and bottom views with dimensions in inches.

Top View Dimensions:

- Overall width: .536 (max), .524 (min)
- Overall height: .710 REF.
- Inner width: .536 (max), .524 (min)
- Distance from left edge to center of pad 2: .075
- Distance between pads 2 and 3: .200
- Distance from center of pad 3 to right edge: .130
- Distance from center of pad 3 to right edge of package: .050

Side View Dimensions:

- Overall height: .260 MAX.
- Distance from top edge to center of pad 1: .015
- Distance from top edge to center of pad 2: .020
- Distance from top edge to center of pad 3: .10
- Distance from top edge to center of pad 4: .185
- Distance from top edge to center of pad 5: .045
- Distance from top edge to center of pad 6: .003
- Distance from top edge to center of pad 7: .004

Bottom View Dimensions:

- Distance from bottom edge to center of pad 1: .005 TYP.
- Distance from bottom edge to center of pad 2: .080
- Distance from bottom edge to center of pad 3: .036 MIN.
- Distance from bottom edge to center of pad 4: .036 MIN.
- Distance from bottom edge to center of pad 5: .030 MIN.

PAD ASSIGNMENTS:

- 1=CATHODE
- 2=N/C
- 3=ANODE

NOTES:

1. DIMENSIONING AND TOLERANCING PER Y14.55SM-1
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS SHOWN IN INCHES.
4. UNLESS NOTED, TOLERANCES ARE ± 0.005 UOS

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